

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Suan J. Boon  
Title: METHOD OF PACKAGING AT A WAFER LEVEL

Docket No.: 303.601US3  
Filed: November 26, 2003  
Examiner: James M. Mitchell

Serial No.: 10/722,838  
Due Date: March 9, 2008  
Group Art Unit: 2813

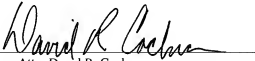
**MS AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

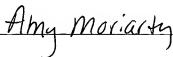
☒ Amendment and Response under 37 CFR 1.116 (11 pgs.).

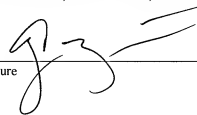
Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7th day of March, 2008.

  
Name

  
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SCHWEGMAN, LUNDBERG & WOESSNER, P.A.

(GENERAL)